SLOVENSKI STANDARD
SIST EN 16602-70-12:2016

01-december-2016

Zagotavljanje varnih proizvodov v vesoljski tehniki - Pravila načtovanja za plošče tiskanih vezij

Space product assurance - Design rules for printed circuit boards

Raumfahrtproduktsicherung - Designregeln für Leiterplatten

Assurance produit des projets spatiaux - Règles de conception des circuits imprimés

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Ta slovenski standard je istoveten z: EN 16602-70-12:2016

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ICS:

31.180	Tiskana vezja (TIV) in tiskane plošče	Printed circuits and boards
49.140	Vesoljski sistemi in operacije	Space systems and operations

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EUROPEAN STANDARD

NORME EUROPÉENNE

EUROPÄISCHE NORM

EN 16602-70-12

October 2016

ICS 31.180; 49.140

English version

Space product assurance - Design rules for printed circuit boards

Assurance produit des projets spatiaux - Règles de conception des circuits imprimés

Raumfahrtproduktsicherung - Designregeln für Leiterplatten

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Ref. No. EN 16602-70-12:2016 E

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Introduction

PCBs are used for the mounting of electronic components to produce PCB assemblies that perform electrical functions. The PCBs are subjected to thermo-mechanical stress during assembly such as soldering of components, rework and repair under normal terrestrial conditions. In addition the assembled PCBs are exposed to the launch and space environment. The reliability of the circuit depends on the robustness of the design, among other factors. Moreover, PCB design with high technological complexity enables the use of complex components with advanced functionality.

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